

# **A Method for Fabricating a Lid for a Wafer Level Packaged Optical MEMS Device**

## **ABSTRACT OF THE DISCLOSURE**

A method of individually packaging a multiplicity of devices, such as a spatial light modulator, before the multiplicity of devices formed on a substrate wafer are separated. The method and structure comprises individually sealing each device while the device is still part of the substrate wafer with an interposer wafer and a cover or window wafer. After each device is sealed by the combination interposer wafer and cover wafer, the combination cover wafer is sawed through down to the substrate wafer. The sealed devices may then be fully separated by scoring and breaking the substrate wafer.